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(21) International Application Number: PCT/US98/23711 (22) International Filing Date: 9 November 1998 (09.11.98) (30) Priority Data: 60/065,418 13 November 1997 (13.11.97) US (71) Applicant (for all designated States except US): AMOCO CORPORATION [US/US]; Law Dept., Mail Code 1907A, 200 E. Randolph Drive, P.O. Box 87703, Chicago, IL 60680-0703 (US). (72) Inventors; and (75) Inventors/Applicants (for US only): LEVESQUE, Kevin, J. [US/US]; 4229 Drew Road, Alpharetta, GA 30004 (US). MILLER, James, D. [US/US]; 3251 Running Cedar Drive, Marietta, GA 30062 (US). (74) Agent: OLIVER, Wallace, L.; Amoco Corporation, Law Dept., Mail Code 1907A, P.O. Box 87703, Chicago, IL 60680-0703 (US).		(81) Designated States: CA, DE, GB, JP, SG, US, European patent (AT, BE, CH, CY, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE). Published <i>With international search report.</i>
(54) Title: HEAT PIPE THERMAL MANAGEMENT APPARATUS		
(57) Abstract A thermal management apparatus comprising a heat pipe component in thermal communication with a molded heat sink component. In a preferred embodiment, the heat sink comprises a filled, thermally conductive, liquid crystal polymer or thermoset resin. Preferably, the thermal management apparatus will be formed as a unitary structure by an insert molding operation.		